

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 09-246732

(43)Date of publication of application : 19.09.1997

(51)Int.Cl. H05K 3/46  
C23F 11/00  
H05K 3/38

(21)Application number : 08-068922

(71)Applicant : IBIDEN CO LTD

(22)Date of filing : 01.03.1996

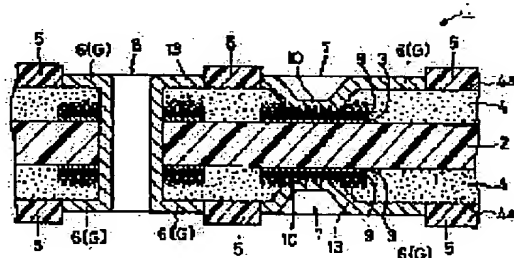
(72)Inventor : KAWADE MASAHIRO  
UNO HIROAKI

## (54) MULTILAYER PRINTED WIRING BOARD AND MANUFACTURING METHOD THEREOF

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a multilayer printed wiring board superior in appearance and reliability even under high temp. high pressure and high humidity conditions.

**SOLUTION:** A multilayer printed wiring board 1 has an inner conductor pattern 3 having a finely roughed layer 9 at the surface and interlayer insulation layer 4 disposed between the inner and outer conductor patterns 3, 6. A rust-preventing agent 13 is disposed between these layers 9, 4 and applied to the surface of a metal or precious metal layer contg. at least one metal having a higher ionization tendency than Cu and lower than Ti; this metal layer being formed on the surface of the surface layer 9 of the pattern 3.



## LEGAL STATUS

[Date of request for examination] 15.07.1999

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2000 Japanese Patent Office